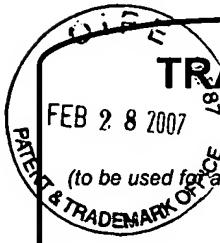


SJM

Please type a plus sign (+) inside this box → +



# TRANSMITTAL FORM

(to be used for all correspondence after initial filing)

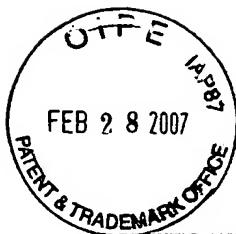
Application Number	10/772,311
Filing Date	February 6, 2004
Inventor(s)	Sang-Hyeop LEE et al.
Group Art Unit	1732
Examiner Name	Lee, Edmund H.
Attorney Docket Number	2557-000220/US

## ENCLOSURES (check all that apply)

<input type="checkbox"/> Fee Transmittal Form	<input type="checkbox"/> Assignment Papers (for an Application)	<input type="checkbox"/> After Allowance Communication to Group
<input type="checkbox"/> Fee Attached	<input type="checkbox"/> Letter to the Official Draftsperson and _____ Sheets of Formal Drawing(s)	<input type="checkbox"/> LETTER SUBMITTING APPEAL BRIEF AND APPEAL BRIEF (w/clean version of pending claims)
<input type="checkbox"/> Amendment	<input type="checkbox"/> Licensing-related Papers	<input type="checkbox"/> Appeal Communication to Group (Notice of Appeal, Brief, Reply Brief)
<input type="checkbox"/> After Final	<input type="checkbox"/> Petition	<input type="checkbox"/> Proprietary Information
<input type="checkbox"/> Affidavits/declaration(s)	<input type="checkbox"/> Petition to Convert to a Provisional Application	<input type="checkbox"/> Status Letter
<input type="checkbox"/> Extension of Time Request	<input type="checkbox"/> Power of Attorney, Revocation Change of Correspondence Address	<input checked="" type="checkbox"/> Other Enclosure(s) (please identify below):
<input type="checkbox"/> Express Abandonment Request	<input type="checkbox"/> Terminal Disclaimer	<b>Response to Restriction Requirement</b>
<input type="checkbox"/> Information Disclosure Statement	<input type="checkbox"/> Request for Refund	
<input type="checkbox"/> Certified Copy of Priority Document(s)	<input type="checkbox"/> CD, Number of CD(s) _____	
<input type="checkbox"/> Response to Missing Parts/ Incomplete Application		
<input type="checkbox"/> Response to Missing Parts under 37 CFR 1.52 or 1.53		
	Remarks	

## SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

Firm or Individual name	Hamess Dickey & Pierce, P.L.C.	Attorney Name	Reg. No.
Signature			
Date	February 28, 2007		



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Sang-Hyeop LEE et al.

Conf. No.: 7420

Serial No.: 10/772,311

Group: 1732

Filed: February 6, 2004

Examiner: Lee, Edmund H.

For: MOLDING METHOD AND MOLD FOR ENCAPSULATING BOTH SIDES  
OF PCB MODULE WITH WAFER LEVEL PACKAGE MOUNTED PCB

Docket No.: 2557-000220/US

**RESPONSE TO RESTRICTION REQUIREMENT**

Customer Service Window  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

February 28, 2007

Dear Sir:

In response to Restriction Requirement set forth in the February 21, 2007 Office Action, the following remarks are respectfully submitted in connection with the above-referenced application.

**Listing of the Claims** begins on page 2 of this response.

**Remarks** begin on page 8 of this response.

	Claims remaining after Amendment		Highest number previously paid for		Present extra
<b>Total</b>	18	-	20	=	0
<b>Independent</b>	3	-	3	=	0